



SOT663

plastic surface-mounted package; 3 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOT663
Package type industry code	SOT663
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.5	-	1.6	1.7	mm
E	package width	1.1	-	1.2	1.3	mm
A	seated height	0.5	-	0.55	0.6	mm
n ₂	actual quantity of termination	-	-	3	-	



2. Package outline

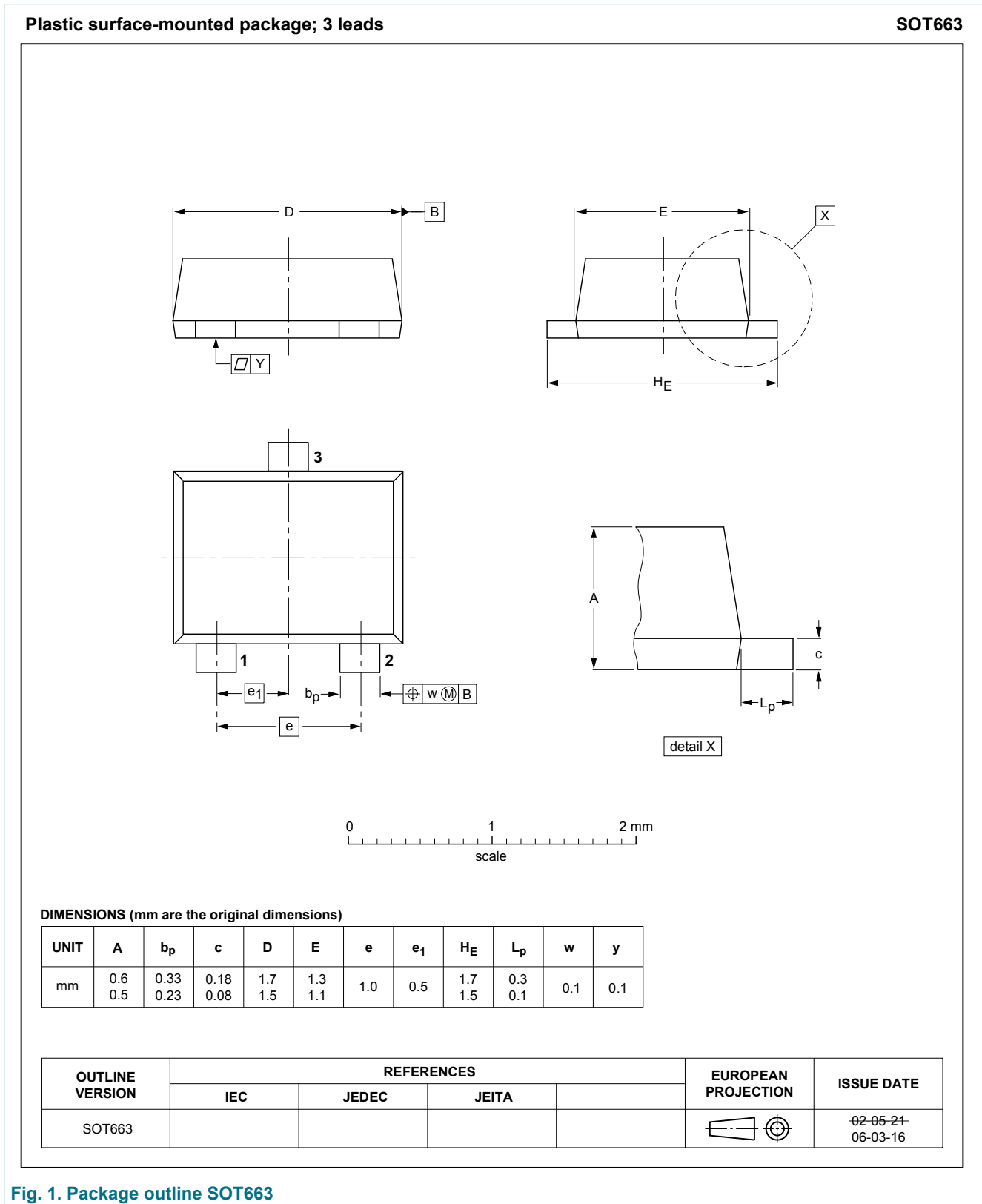
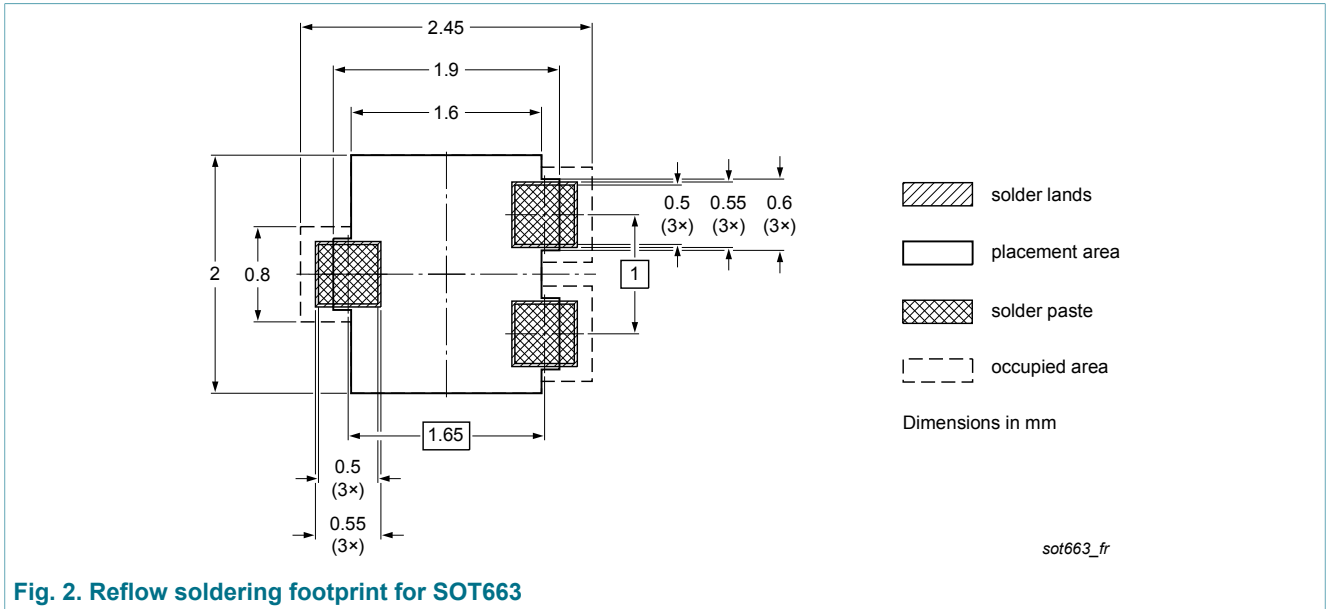


Fig. 1. Package outline SOT663

3. Soldering



4. Legal information

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Date of release: 8 February 2016
